



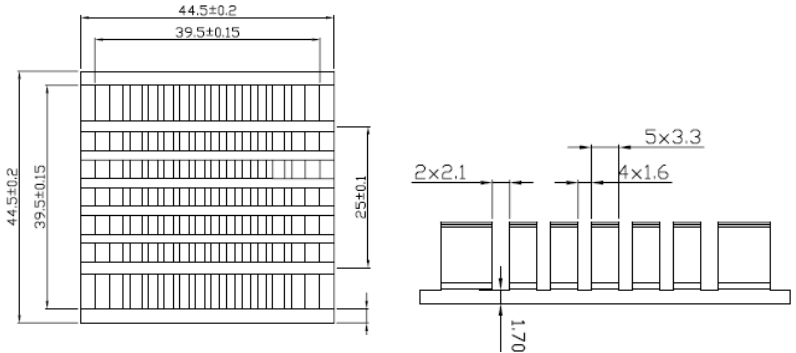
Model : CBGA0045451000-01

BGA Heat Sink Specification

For 45x45 Chip set



- 1. Material : Al 6063
- 2. Dimension :
Foot print : 45x45mm
Height : 10 mm
Base (thickness) : 1.7mm
- 3. Finish: Black Anodize
- 4. Accessory :
Clip : Plastic (UL94-V0)
Thermal pad : 8612I or others



Performance

Heat Source (LxW)	15x15
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